

Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 02/19/2007

Product Category: Linear Devices; Mixed Signal Devices;
24xxx; 25xxx; PIC16xxx; PSxxx

Notification Subject: Change #720: Qualify 14L TSSOP With
G700 Mold Compound, 8290 Die Attach
Epoxy, And Stamped Leadframe At UNIS

Notification Body:

Microchip Part#s Affected:

MCP6274
MCP6024
MCP609
MCP6004
MCP6G04
MCP6274
MCP6284
MCP6294
MCP6274
MCP6G44
MCP6234
MCP6244
MCP6044
MCP6144
MCP6544
MCP6549
MCP604
MCP42050
MCP42100
MCP42010
MCP4922
MCP3302
MCP4231
MCP4241
MCP4251
MCP4261
MCP3204
MCP3004
24AA512
24LC512
24FC512
25AA320
25C320

25LC320
PIC16F676
PIC16F688
PIC16F630
PIC16C505
PIC16LC505
PIC16F684
PIC16F636
PIC16F616
PIC16HV616
PIC16F610
PIC16HV610
PIC16F506
PIC16F505
PS810

Description of Change:
CHANGE BILL OF MATERIALS

Impacts to Data Sheet:
NONE

Reason for Change:
IMPROVED MANUFACTURABILITY, USE OF "GREEN" MATERIALS

Estimated Change Implementation Date(s):
MARCH 31, 2007

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date
Code, Device Marking, Ship Container Marking)
TRACEABILITY CODE
